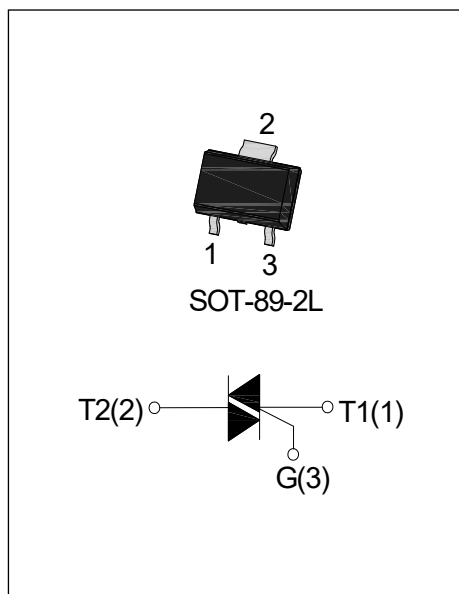




DESCRIPTION:

With low holding and latching current, JST131N2-600D triacs are especially recommended for use on middle and small resistance type power load. Package SOT-89-2L is RoHScompliant. (2011/65/EU)



MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	1	A
I_{TSM}	16	A
V_{TM}	≤ 1.5	V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T_{stg}	-40 - 150	$^{\circ}C$
Operating junction temperature range	T_j	-40 - 125	$^{\circ}C$
Repetitive peak off-state voltage ($T_j=25^{\circ}C$)	V_{DRM}	600	V
Repetitive peak reverse voltage ($T_j=25^{\circ}C$)	V_{RRM}	600	V
RMS on-state current	$I_{T(RMS)}$	1	A
SOT-89-2L ($T_C=75^{\circ}C$)			
Non repetitive surge peak on-state current (full cycle, F=50Hz)	I_{TSM}	16	A
I^2t value for fusing ($t_p=10ms$)	I^2t	1.28	A^2s
Critical rate of rise of on-state current ($I_G=2 \times I_{GT}$)	di/dt	20	$A/\mu s$
Peak gate current	I_{GM}	2	A
Average gate power dissipation	$P_{G(AV)}$	0.5	W
Peak gate power	P_{GM}	5	W
Peak pulse voltage ($T_j=25^{\circ}C$; non-repetitive, off-state; FIG.7)	V_{PP}	2.5	kV

ELECTRICAL CHARACTERISTICS (T_j=25°C unless otherwise specified)

Symbol	Test Condition	Quadrant		Value	Unit
I _{GT}	V _D =12V R _L =33Ω	I - II -III	MAX	5	mA
		IV		10	
V _{GT}		ALL	MAX	1.3	V
V _{GD}	V _D =V _{DRM} T _j =125°C R _L =3.3KΩ	ALL	MIN	0.2	V
I _L	I _G =1.2I _{GT}	I -III-IV	MAX	5	mA
		II		20	
I _H	I _T =200mA		MAX	7	mA
dv/dt	V _D =2/3V _{DRM} Gate Open T _j =125°C		MIN	20	V/μs
(dv/dt) _c	(di/dt) _c =0.44A/ms, T _j =110°C		MIN	1	V/μs

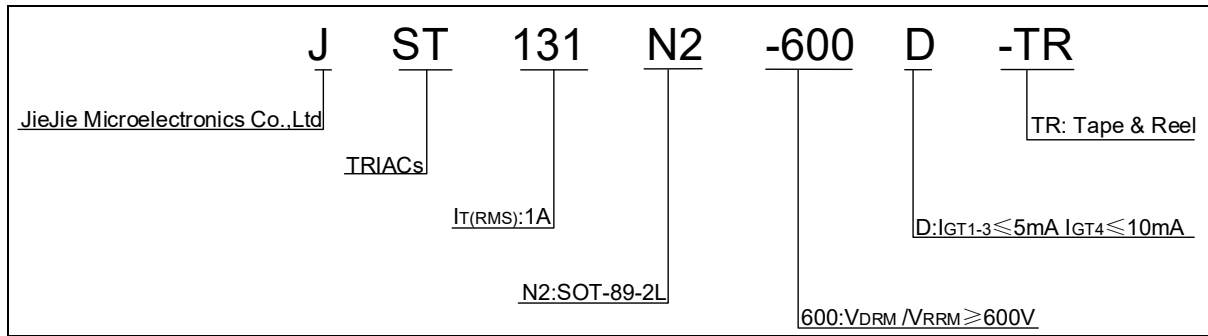
STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V _{TM}	I _{TM} =1.4A tp=380μs	T _j =25°C	1.5	V
V _{TO}	Threshold voltage	T _j =125°C	0.95	V
R _d	Dynamic resistance	T _j =125°C	256	mΩ
I _{DRM}	V _D =V _{DRM} V _R =V _{RRM}	T _j =25°C	5	μA
I _{RRM}		T _j =125°C	0.5	mA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th(j-c)}	junction to case(AC)	SOT-89-2L	31	°C/W
R _{th(j-a)}	junction to ambient	SOT-89-2L	64	°C/W

ORDERING INFORMATION



MARKING

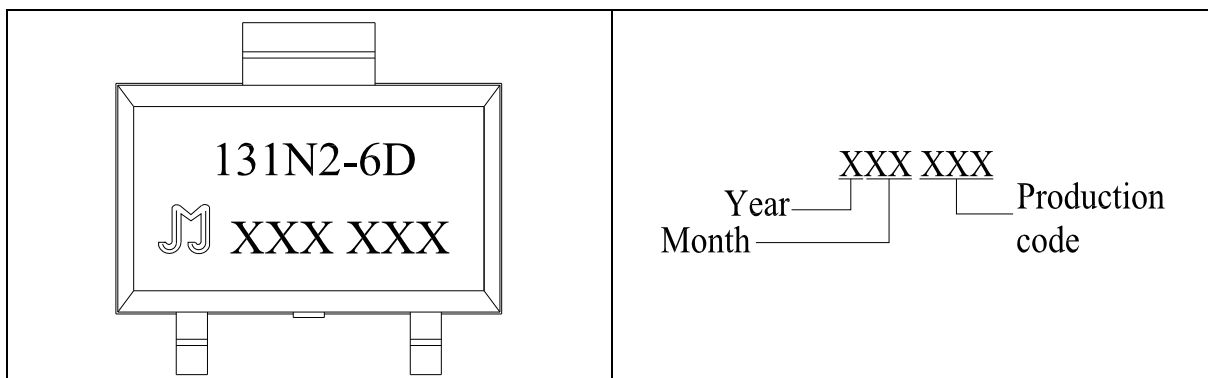


FIG.1: Maximum power dissipation versus RMS on-state current

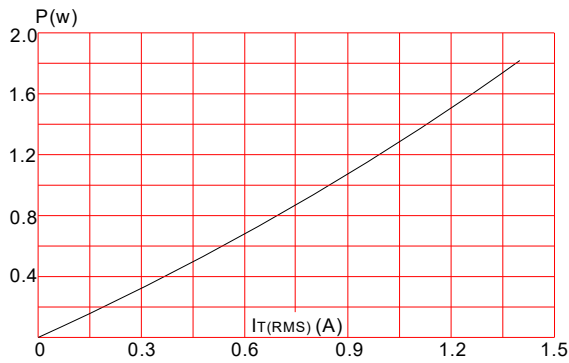


FIG.2: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35μm) (full cycle)

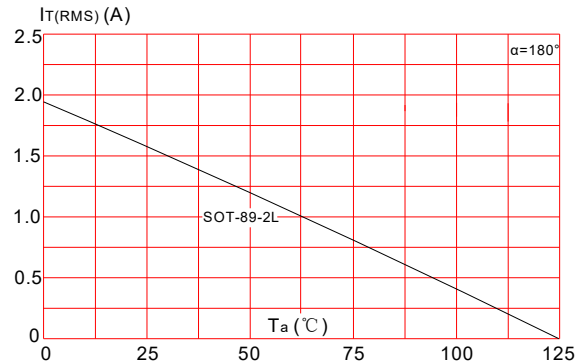


FIG.3: Surge peak on-state current versus number of cycles

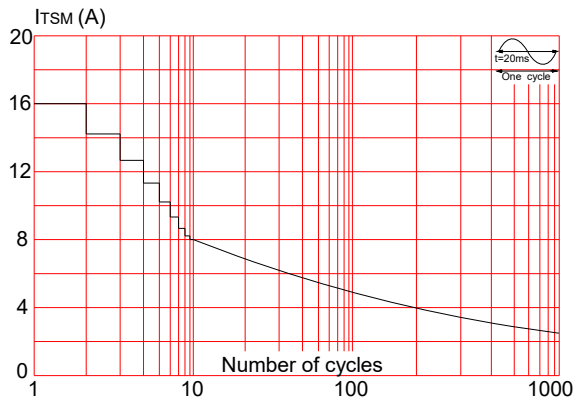


FIG.4: On-state characteristics (maximum values)

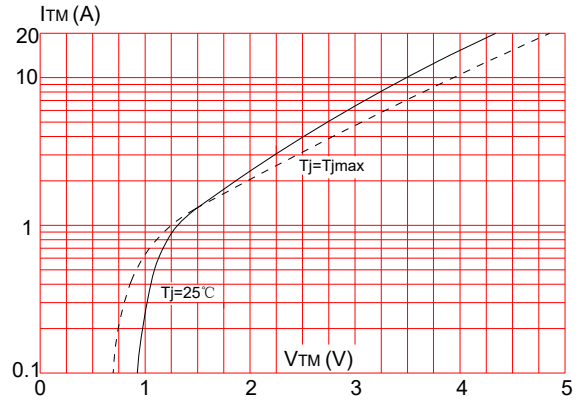


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$ and corresponding value of I^2t ($di/dt < 20\text{A}/\mu\text{s}$)

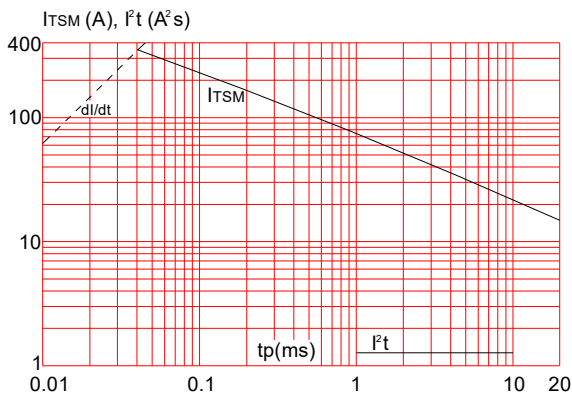


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

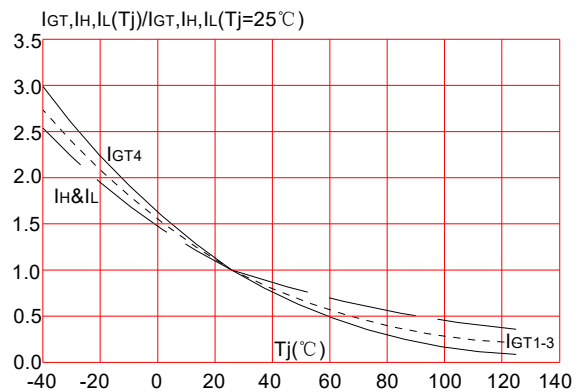
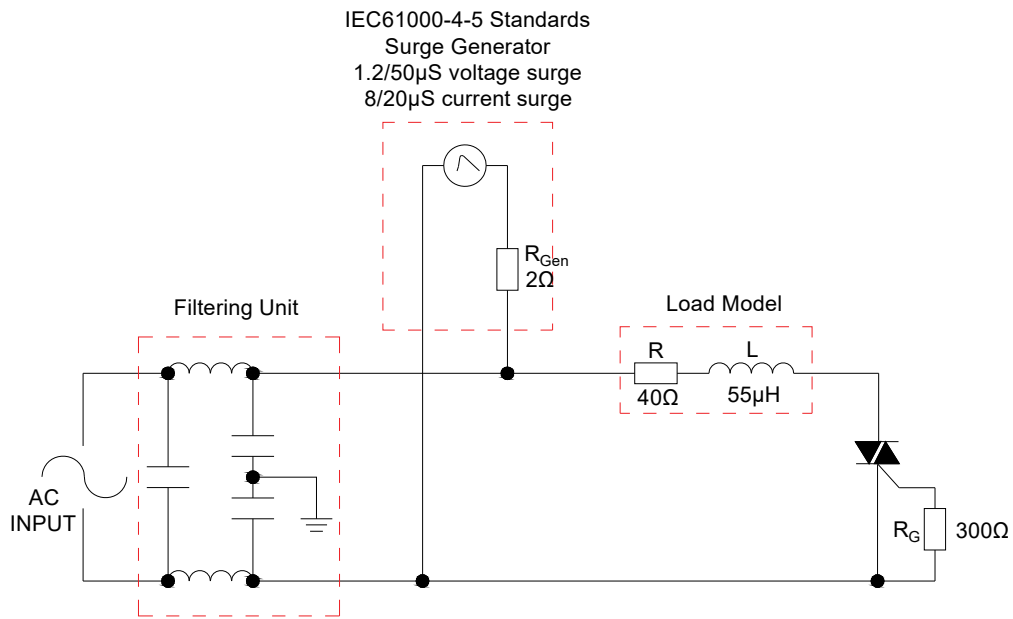
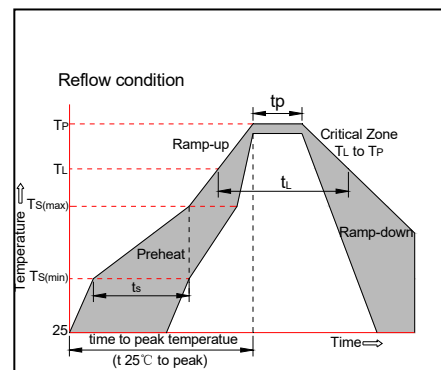


FIG.7: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards.



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



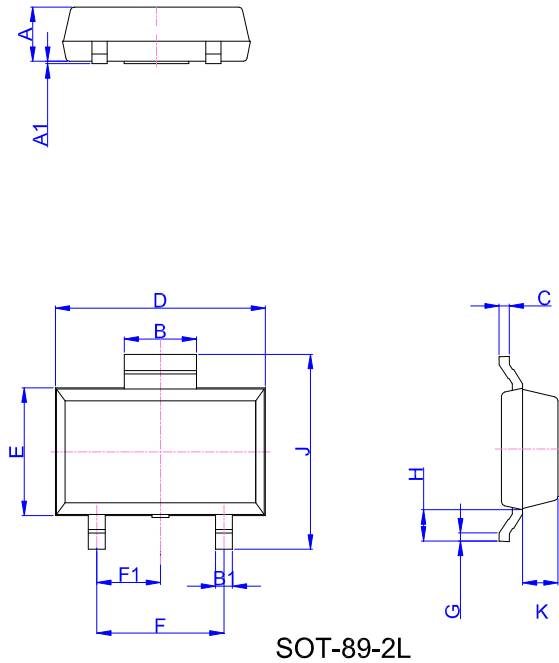
ORDERING INFORMATION

Order code	Voltage V _{DRM} /V _{R_{RM}} (V)	IGT(mA)		Package	Base qty. (pcs)	Delivery mode
		I -II-III	IV			
JST131N2-600D	600	5	10	SOT-89-2L	4,000	Tape & Reel

Document Revision History

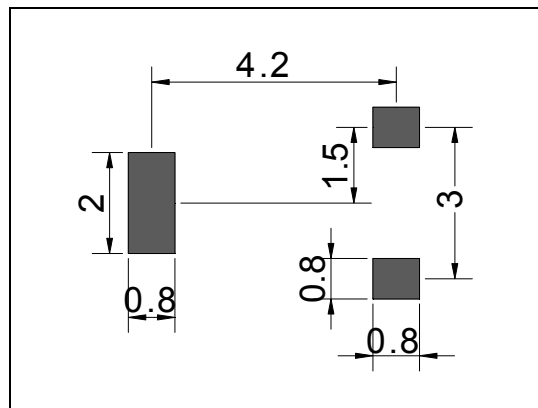
Date	Revision	Changes
Mar 26, 2022	1	Last update

PACKAGE MECHANICAL DATA

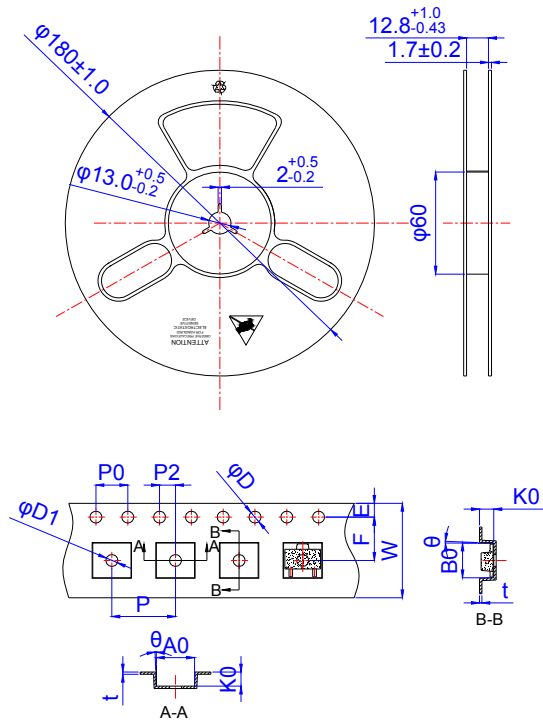


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.3	1.4	1.5	0.051	0.055	0.059
A1	0.01	0.06	0.10	0.001	0.002	0.004
B	1.6	1.7	1.8	0.063	0.067	0.071
B1	0.3	0.4	0.5	0.012	0.016	0.020
C	0.22	0.254	0.32	0.009	0.010	0.013
D	4.75	4.95	5.15	0.187	0.195	0.203
E	2.75	2.95	3.15	0.108	0.116	0.124
F		3.0			0.118	
F1		1.5			0.059	
G	0.2	0.3	0.4	0.008	0.012	0.016
H	0.58	0.78	0.98	0.023	0.031	0.039
J	4.3	4.5	4.7	0.169	0.177	0.185
K		0.88			0.035	

FOOTPRINT-SOT-89-2L (dimensions in mm)



DELIVERY MODE



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
E	1.65	1.75	1.85	0.065	0.069	0.073
F	5.45	5.50	5.55	0.215	0.217	0.219
P2	1.95	2.00	2.05	0.077	0.079	0.081
D	-	1.50	1.60	-	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
10P0	39.80	40.00	40.20	1.567	1.575	1.583
W	11.90	12.00	12.10	0.469	0.472	0.476
P	7.90	8.00	8.10	0.311	0.315	0.319
A0	4.70	4.80	4.90	0.185	0.189	0.193
B0	4.30	4.40	4.50	0.169	0.173	0.177
K0	1.70	1.80	1.90	0.067	0.071	0.075
t	0.25	0.30	0.35	0.010	0.012	0.014
θ	3°		5°	3°		5°

PACKAGE	OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
SOT-89-2L	TAPING	4,000	40,000	13 inch



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